MICROCHIF

Міскоснір						Package Homogeneous Materials				
Semiconductor Device Type:	S8B	VQFN 32 5x5x1mm Matte Tin								
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	5.20	(mg) Total	Die	% of Total Weight	7.
Silicon	7440-21-3	Die	7.88	5.20	78788		Silicon	7440-21-3	100.00	
Copper	7440-50-8	Lead Frame	39.81	26.27	398056	Total 100.00				
Iron	7439-89-6	Lead Frame	1.01	0.67	10120					
Lead	7439-92-1	Lead Frame	0.00	0.00	22	27.00	(mg) Total	Lead Frame	% of Total Weight	40
Phosphorus	7723-14-0	Lead Frame	0.04	0.02	355		Copper	7440-50-8	97.30	
Zinc	7440-66-6	Lead Frame	0.05	0.04	538		Iron	7439-89-6	2.47	
Silver	7440-22-4	Lead Frame Plating	0.15	0.10	1515		Lead	7439-92-1	0.01	
Silver	7440-22-4	Die Attach	1.06	0.70	10585		Phosphorus	7723-14-0	0.09	
Isobornyl Methacrylate	7534-94-3	Die Attach	0.07	0.05	727		Zinc	7440-66-6	0.13	
Lauryl Acrylate	2156-97-0	Die Attach	0.07	0.05	727			Total	100.00	
1,6-Hexanediol Diacrylate	13048-33-4	Die Attach	0.01	0.00	73					
N-Methyl-2-Pyrroliodone	872-50-4	Die Attach	0.00	0.00	9	0.10	(mg) Total	Lead Frame Plating	% of Total Weight	(
Epoxy Resin	Trade Secret	Mold Compound	3.88	2.56	38788		Silver	7440-22-4	100.00	
Phenol Resin	Trade Secret	Mold Compound	2.42	1.60	24242			Total	100.00	
Metal Hydroxide	Trade Secret	Mold Compound	0.73	0.48	7273					
Carbon Black	1333-86-4	Mold Compound	0.24	0.16	2424	0.80	(mg) Total	Die Attach	% of Total Weight	
Silica Fused	60676-86-0	Mold Compound	41.21	27.20	412121		Silver	7440-22-4	87.33	
Gold	7440-57-5	Bond Wire	0.61	0.40	6061		Isobornyl Methacrylate	7534-94-3	6.00	
Tin	7440-31-5	Lead Finish Plating	0.76	0.50	7576		Lauryl Acrylate	2156-97-0	6.00	
TOTALS: 100.00 66.00 1,000 66.00 mg Total Mass					1,000,000		1,6-Hexanediol Diacrylate	13048-33-4	0.60	
							N-Methyl-2-Pyrroliodone	872-50-4	0.08	
		-						Total	100.00	

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of

Microchip Technology Incorporated designs all products to comply with global product material compliance standards, including but not limited to RoHS, REACH, and China RoHS. Additionally, Microchip products are designed to be compliant with IEC62474. For specific compliance information, please check our product material compliance website on microchip.com or ask your local sales representative.

Microchip Technology Incorporated believes the information in this MCD is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Safety Data Sheets provided by yaw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have become reprovided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts. These estimates do not include trace levels of dopants, impurities, metals, and non-metallic materials which may be contained within silicon devices (silicon (C) or the finished parts

Microchip Technology Incorporated does not provide any warranty, express or implied, with respect to the Information provided in this declaration. The exclusive, limited product warranties provided by Microchip Technology Incorporated, and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's quotations, sales order acknowledgements, and invoices.

Microchip disclaims any duty to notify users of updates or changes to MCDs and shall not be liable for any damages, direct or indirect, consequential or otherwise, suffered by users or third parties as a result of the users' reliance on the information in MCDs.

	N-Methyl-2-Pyrroliodone	872-50-4	0.08	
	•	Total	100.00	
32.00	(mg) Total	Mold Compound	% of Total Weight	48.48
	Epoxy Resin	Trade Secret	8.00	
	Phenol Resin	Trade Secret	5.00	
	Metal Hydroxide	Trade Secret	1.50	
	Carbon Black	1333-86-4	0.50	
	Silica Fused	60676-86-0	85.00	
		Total	100.00	
	(\ T - 4 - 1		a/ 4=	0.04
0.40	(mg) Total	Bond Wire	% of Total Weight	0.61
0.40	(mg) Total Gold	Bond Wire 7440-57-5	% of Total Weight 100.00	0.61
0.40				0.61
0.40		7440-57-5	100.00	0.61
	Gold	7440-57-5 Total	100.00 100.00	

G700LTD_A194_3280 9:02 AM : 11/15/2024